### INTEGRATED CIRCUITS

## DATA SHEET

# **74F245**Octal transceiver (3-State)

Product specification

1994 Nov 15

IC15 Data Handbook

## **Philips Semiconductors**





74F245

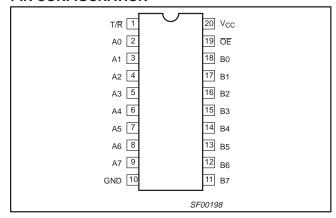
#### **FEATURES**

- Octal bidirectional bus interface
- 3-State buffer outputs sink 64mA
- 15mA source current
- Outputs are placed in high impedance state during power-off conditions

#### **DESCRIPTION**

The 74F245 is an octal transceiver featuring non-inverting 3-State bus compatible outputs in both transmit and receive directions. The B port outputs are capable of sinking 64mA and sourcing 15mA, producing very good capacitive drive characteristics. The device features an Output Enable  $(\overline{\text{OE}})$  input for easy cascading and Transmit/Receive (T/R) input for direction control. The 3-State outputs, B0–B7, have been designed to prevent output bus loading if the power is removed from the device.

#### **PIN CONFIGURATION**



TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F245	4.0ns	70mA

#### ORDERING INFORMATION

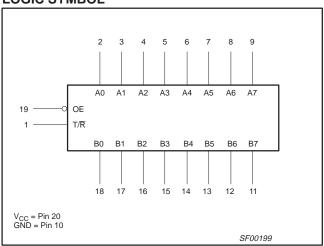
DESCRIPTION	COMMERCIAL RANGE V <sub>CC</sub> = 5V ±10%, T <sub>amb</sub> = 0°C to +70°C	DRAWING NUMBER
20-Pin Plastic DIP	N74F245N	SOT146-1
20-Pin Plastic SO	N74F245D	SOT163-1
20-Pin Plastic SSOP Type II	N74F245DB	SOT339-1

#### INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

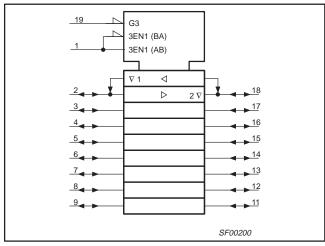
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
A0-A7, B0-B7	Data inputs	3.5/1.0	70μA/0.6mA
ŌĒ	Output Enable input (active Low)	1.0/2.0	20μA/1.2mA
T/R	Transmit/Receive input	1.0/2.0	20μA/1.2mA
A0-A7	A port outputs	150/40	3.0mA/24mA
B0-B7	B port outputs	750/106.7	15mA/64mA

**NOTE:** One (1.0) FAST unit load is defined as: 20μA in the High state and 0.6mA in the Low state.

#### LOGIC SYMBOL

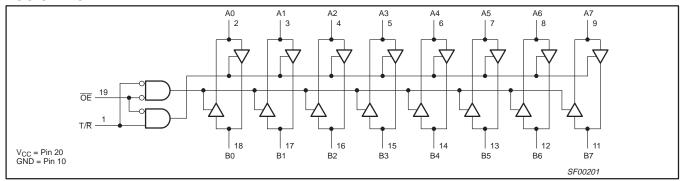


#### **IEC/IEEE SYMBOL**



74F245

#### **LOGIC DIAGRAM**



#### **FUNCTION TABLE**

INP	UTS	OUTPUTS
ŌĒ	T/R	0017013
L	L	Bus B data to Bus A
L	Н	Bus A data to Bus B
Н	Х	Z

H = High voltage level

L = Low voltage level

X = Don't care

Z = High impedance "off" state

#### **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT	
V <sub>CC</sub>	Supply voltage		-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage		-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA	
V <sub>OUT</sub>	Voltage applied to output in High output state	-0.5 to +5.5	V	
	Current applied to output in Low output state	A0-A7	48	mA
IOUT	Current applied to output in Low output state	B0-B7	128	mA
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C	
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C	

#### **RECOMMENDED OPERATING CONDITIONS**

CVMDOL	DADAMETED		UNIT			
SYMBOL	PARAMETER	MIN	NOM	MAX	UNII	
V <sub>CC</sub>	Supply voltage		4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage		2.0			V
V <sub>IL</sub>	Low-level input voltage			0.8	V	
I <sub>IK</sub>	Input clamp current			-18	mA	
	High-level output current	A0–A7			-3	mA
ГОН	nigh-lever output current	B0-B7			-15	mA
	Low level output ourrent	A0–A7			24	mA
I <sub>OL</sub>	Low-level output current			64	mA	
T <sub>amb</sub>	Operating free-air temperature range		0		+70	°C

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#### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	DADAMETE	В		T CONDITIONS		UNIT			
STWBUL	PARAMETE	FARAMETER			TEST CONDITIONS <sup>1</sup>				
		A0-A7, B0-B7		)	±10% V <sub>CC</sub>	2.4			V
V	I light level evident value	AU-A7, BU-B7	$V_{CC} = MIN,$ $V_{IL} = MAX,$	$I_{OH} = -3mA$	±5% V <sub>CC</sub>	2.7	3.4		V
V <sub>OH</sub>	High-level output voltage	B0-B7	$V_{IH} = MIN$	1 15m A	±10% V <sub>CC</sub>	2.0			V
		BU-B7		$I_{OH} = -15 \text{mA}$	±5% V <sub>CC</sub>	2.0			V
		A0-A7	V <sub>CC</sub> = MIN,	$I_{OL} = 20mA$	±10% V <sub>CC</sub>		0.30	0.50	V
$V_{OL}$	Low-level output voltage	A0-A7	$V_{IL} = MAX$	$I_{OL} = 24mA$	±5% V <sub>CC</sub>		0.35	0.50	V
		B0-B7	V <sub>IH</sub> = MIN	$I_{OL} = MAX$	±10% V <sub>CC</sub>			0.55	V
V <sub>OL</sub>	Low-level output voltage	B0-B7	$V_{CC} = MIN,$ $V_{IL} = MAX,$ $V_{IH} = MIN$	I <sub>OL</sub> = MAX	±5% V <sub>CC</sub>		0.42	0.55	V
V <sub>IK</sub>	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$				-0.73	-1.2	V
	Input current at maximum	ŌĒ, T/R	$V_{CC} = 5.5V, V_{I}$	V <sub>CC</sub> = 5.5V, V <sub>I</sub> = 7.0V				100	μΑ
ΙΙ	input voltage	A0-A7, B0-B7	$V_{CC} = 5.5V, V_{I}$	= 5.5V				1	mA
I <sub>IH</sub>	High-level input current	OE, T/R only	$V_{CC} = MAX, V_I$	= 2.7V				20	μΑ
I <sub>IL</sub>	Low-level input current	OE, T/R only	$V_{CC} = MAX, V_I$	= 0.5V				-1.2	mA
I <sub>IH</sub> +I <sub>OZH</sub>	Off-state output current High level voltage applied		$V_{CC} = MAX, V_{CC}$	<sub>O</sub> = 2.7V				70	μΑ
I <sub>IL</sub> +I <sub>OZL</sub>	Off-state output current Low level voltage applied		V <sub>CC</sub> = MAX, V <sub>0</sub>			-600	μΑ		
	Chart circuit output ourrant3	A0-A7	\/ _ MAX	N. MAN		-60		-150	mA
los	Short-circuit output current <sup>3</sup> B0-		V <sub>CC</sub> = MAX			-100		-225	mA
		I <sub>CCH</sub>					60	87	mA
$I_{CC}$	Supply current (total)	I <sub>CCL</sub>	$V_{CC} = MAX$				70	100	mA
		I <sub>CCZ</sub>					75	110	mA

#### **AC ELECTRICAL CHARACTERISTICS**

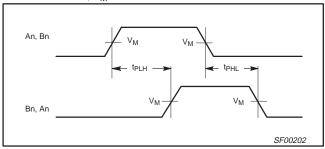
SYMBOL	PARAMETER	TEST CONDITION	$V_{CC} = +5.0V$ $T_{amb} = +25^{\circ}C$ $C_{L} = 50pF, R_{L} = 500\Omega$			V <sub>CC</sub> = +5. T <sub>amb</sub> = 0°C C <sub>L</sub> = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay An to Bn, Bn to An	Waveform 1	2.5 2.5	3.5 4.0	6.0 6.0	2.5 2.5	7.0 7.0	ns
t <sub>PZH</sub>	Output Enable time to High or Low level	Waveform 2 Waveform 3	2.0 3.5	4.5 5.5	7.0 8.0	2.0 3.5	8.0 9.0	ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output Disable time from High or Low level	Waveform 2 Waveform 3	2.5 1.0	5.0 3.5	6.5 6.0	2.0 1.0	7.5 7.0	ns

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
 All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
 Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

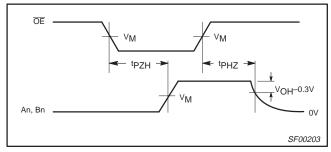
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#### **AC WAVEFORMS**

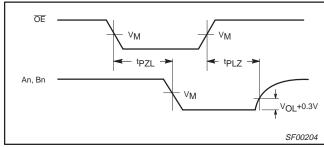
For all waveforms,  $V_M = 1.5V$ .



Waveform 1. Propagation Delay for Non-Inverting Output

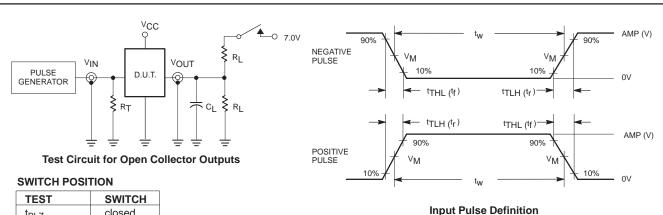


Waveform 2. 3-State Output Enable Time to High Level and Output Disable Time from High Level



Waveform 3. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

#### **TEST CIRCUIT AND WAVEFORMS**



1_

#### **DEFINITIONS:**

R<sub>L</sub> = Load resistor;

see AC electrical characteristics for value.

 $\begin{array}{ll} C_L &=& Load \ capacitance \ includes \ jig \ and \ probe \ capacitance; \\ & see \ AC \ electrical \ characteristics \ for \ value. \end{array}$ 

R<sub>T</sub> = Termination resistance should be equal to Z<sub>OUT</sub> of pulse generators.

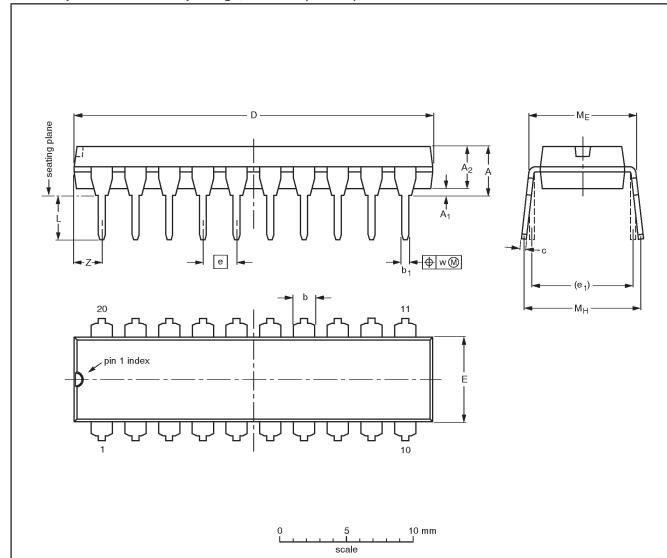
family	INPUT PULSE REQUIREMENTS										
family	amplitude V <sub>M</sub> rep. rate t <sub>w</sub> t <sub>TLH</sub> t <sub>TH</sub>										
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns					

SF00128

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#### DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ	PROJECTION	1990E DATE	
SOT146-1			SC603		<del>92-11-17</del> 95-05-24	

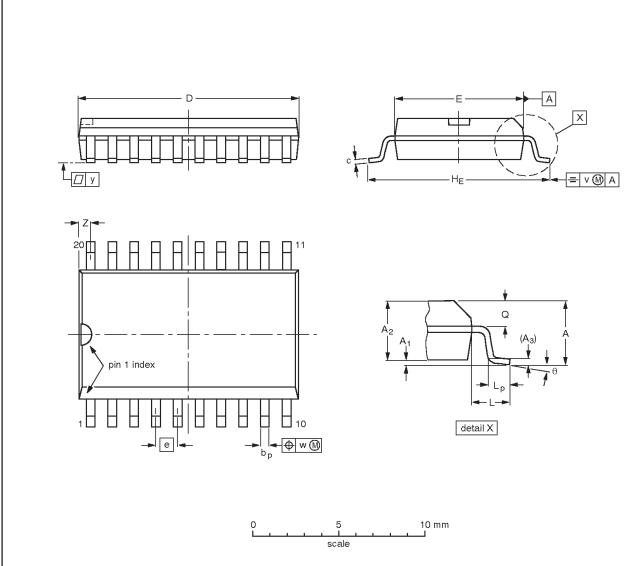
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#### SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	Ьp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013AC				<del>-95-01-24</del> 97-05-22	

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Philips Semiconductors Product specification

Octal transceiver (3-State)

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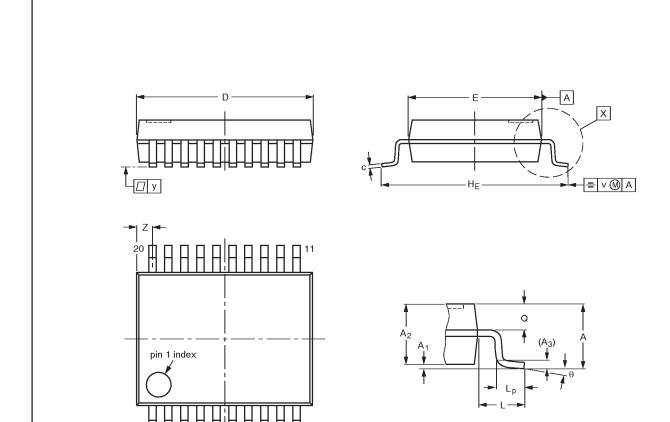
**NOTES** 

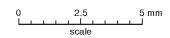
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#### SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1





detail X

#### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	bр	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

#### Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUEDATE	
SOT339-1		MO-150AE				<del>93-09-08</del> 95-02-04	

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DEFINITIONS							
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